

Inform

ECN Overview

Production Process

Fujitsu Mainboards

ECN-No. BSA 1-2015

Reason for ECN: Change in wave soldering process
without any impact on mainboard form, fit and function.

Shipping details: Shipment of mainboards manufactured with new process will be a running change,
expected to start mid of July 2015.

Mainboards in general:

Mainboard	Version	Features	Reason for ECN	ECN Date
All	All		Change in the wave soldering process: Replacement of CuSn solder by BiSnAg solder <ul style="list-style-type: none">• Better hole fill for through hole components (IPC-A-610E)• Reduction of thermal stress for all components• Less board warpage due to production process	07/2015